

AMENDMENTS TO THE SPECIFICATION

In accordance with 37 C.F.R. § 1.121(b)(1)(iii) , on page 1 of the published pending U.S. Patent Application Serial No. US 2002/0067364, please insert the following paragraph after the title of the invention and before the Field of the Invention header:

The instant application claims the benefit of U.S. Provisional Application Serial No. 60/213,349 filed on June 22, 2000 and incorporated-by-reference herein.

- Please amend paragraph [0026] as follows:

[0026] Die 2.1 design data can be communicated to the invention via the GDSII format, a standard in the die design industry. Enclosure 2.2 design data can be communicated to the invention via various enclosure/board level data formats ~~listed in the Appendix~~.

- Please amend paragraph [0030] as follows:

[0030] Die 2.1 design data can be communicated to the invention via the GDSII format, a standard in the die design industry. Enclosure 2.2 design data can be communicated to the invention via various enclosure/board level data formats ~~listed in the Appendix~~.

- Please amend paragraph [0034] as follows:

[0034] Enclosure 2.2 and board 2.3 design data can be communicated to the invention via various enclosure/board level data formats ~~listed in the Appendix~~.

- Please amend paragraph [0039] as follows:

[0039] Board 2.3 design data can be communicated to the invention via various schematic/layout data formats ~~listed in the Appendix~~.

- Please amend paragraph [0043] as follows:

[0043] Board 2.2 design data can be communicated to the invention via various layout data formats ~~listed in the Appendix~~.

- Please amend paragraph [0091] as follows:

[0091] Export modules are used to extract data from the memory resident Data Model 3.4. These modules communicate with the Data Model 3.4 through an open API that is particular to the OS platform. ~~(is this 'export module' the same as the scripting language?)~~